

# CHEMTRONICS®

## Technical Data Sheet

**TDS # SWick**

### Soder-Wick® Desoldering Braid

#### PRODUCT DESCRIPTION

Soder-Wick® offers the state of the art in desoldering technology. Soder-Wick® is designed for today's heat sensitive electronic components using lighter mass, pure copper braid construction that allows for better thermal conductivity, even at low temperatures. Soder-Wick® responds faster than conventional desoldering braids thereby minimizing overheating and preventing PCB damage. A full range of sizes and flux types are available, including Rosin, No Clean, unfluxed and a high temperature Lead-Free version. Whatever the requirement, Soder-Wick® has the answer.

- Requires little or no post solder cleaning
- No corrosive residues
- Optimized construction for faster wicking and heat transfer
- Halide free
- Minimizes the risk of heat damage to components and circuit boards

#### TYPICAL APPLICATIONS

Soder-Wick® desoldering braid safely removes solder from:

- Thru-hole Components
- SMT Pads and BGA Pads
- Micro Circuits
- Terminals
- Lugs and Posts
- Identification Script

#### TYPICAL PRODUCT DATA AND PHYSICAL PROPERTIES

| <b>Flux Types:</b>         | Rosin Grade WW, Type "R"<br>Patented No Clean<br>High Temperature No Clean           |        |              |
|----------------------------|--------------------------------------------------------------------------------------|--------|--------------|
| <b>Specifications:</b>     | ANSI/IPC J STD-004<br>MIL-F-14256 F                                                  |        |              |
| <b>No Clean Flux Spec:</b> | MIL-STD-883B<br>Bellcore TR-NWT-000078<br>ANSI/IPC J SF818                           |        |              |
| <b>Shelflife:</b>          | 2 years                                                                              |        |              |
| <b>RoHS/WEEE Status</b>    |  |        |              |
| Size #                     | Width Inches                                                                         | Color  | Width Metric |
| 1                          | .030"                                                                                | White  | 0.8mm        |
| 2                          | .060"                                                                                | Yellow | 1.5mm        |
| 3                          | .080"                                                                                | Green  | 2.0mm        |
| 4                          | .110"                                                                                | Blue   | 2.8mm        |
| 5                          | .145"                                                                                | Brown  | 3.7mm        |
| 6                          | .210"                                                                                | Red    | 5.3mm        |
| BGA                        | -                                                                                    | Purple | -            |

#### STATIC DISSIPATIVE PACKAGING

Soder-Wick® SD is packaged on Static Dissipative bobbins in 5 and 10-foot lengths to minimize the risk of damage associated with static electricity. The static dissipative bobbins qualify as electrostatic discharge protective per MIL-STD-1686C and MIL-HDBK-263B, and meet the static delay rate provision of MIL-B-81705C.

## USAGE INSTRUCTIONS

For industrial use only.

Read MSDS carefully prior to use.

- 1) Choose a Soder-Wick® desoldering braid width equal to or slightly larger than the pad or connection.
- 2) Choose a solder iron tip equal to or slightly larger than the pad or connection.
- 3) Set temperature of iron between 600-750°F
- 4) Place wick on solder joint and place tip of hot iron on top of wick
- 5) As solder becomes molten, the color of the wick will change from copper to silver.
- 6) Remove wick and iron from solder joint simultaneously once color change has stopped.
- 7) The component lead / pad is now clean and free from solder.
- 8) Clip and discard the used portion of the wick.
- 9) If needed, clean PCB with CircuitWorks® Flux Remover Pen and remove soils with a ControlWipes™ absorbent wipe.

## SODER-WICK® IS DESIGNED TO MEET OR EXCEED THE FOLLOWING:

MIL-F-14256F, Type R  
NASA-STD-8739.3  
DOD-STD-883E, Method 2022  
ANSI/IPC J STD-004, Type ROL0  
BELLCORE TR-NWT-000078  
ANSI/IPC J SF-818

## SODER-WICK® SD BOBBINS ARE DESIGNED TO MEET OR EXCEED:

MIL-STD-2000A  
MIL-B-81705C  
MIL-STD-1686C  
MIL-HDBK-263B

## TECHNICAL & APPLICATION ASSISTANCE

Chemtronics® provides a technical hotline to answer your technical and application related questions. The toll free number is: **1-800-TECH-401.**

## AVAILABILITY

### Series:

- 40** Soder-Wick® Lead-Free, SD Bobbin
- 50** Soder-Wick® Rosin
- 80** Soder-Wick® Rosin, SD Bobbin
- 60** Soder-Wick® No Clean, SD Bobbin
- 70** Soder-Wick® Unfluxed
- 75** Soder-Wick® Unfluxed, SD Bobbin

### ***VacuPak™ Packaging***

The VacuPak Can contains ten five-foot bobbins in a vacuum sealed can. This package provides the highest level of cleanliness and freshness. Great for tool kit storage.

### HELPFUL HINTS:

**Water Soluble Users:** Use Soder-Wick® Unfluxed **70** or **75** Series to dip in water soluble flux and then desolder normally.

**Ball Grid Array:** Use Soder-Wick® BGA with a large tipped iron to remove solder from a number of BGA pads all at once.

**NOTE:** This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. ITW CHEMTRONICS® does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.

Chemtronics®, Soder-Wick® and CircuitWorks® are registered trademarks of ITW Chemtronics. All rights reserved. VacuPak™ and ControlWipes™ are trademarks of ITW Chemtronics. All rights reserved.

### MANUFACTURED BY:

ITW Chemtronics®  
8125 Cobb Center Drive  
Kennesaw, GA 30152  
1-770-424-4888

REV. F (06/06)

### DISTRIBUTED BY:



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

**Телефон:** 8 (812) 309 58 32 (многоканальный)

**Факс:** 8 (812) 320-02-42

**Электронная почта:** [org@eplast1.ru](mailto:org@eplast1.ru)

**Адрес:** 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.